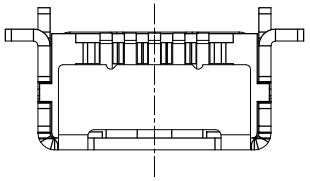
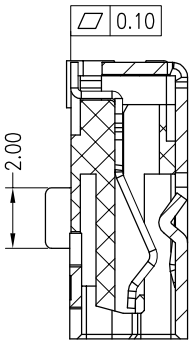
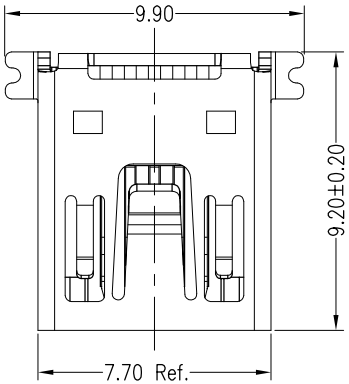
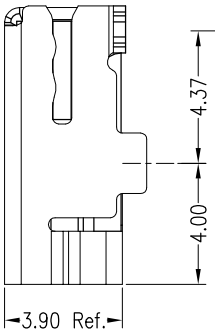
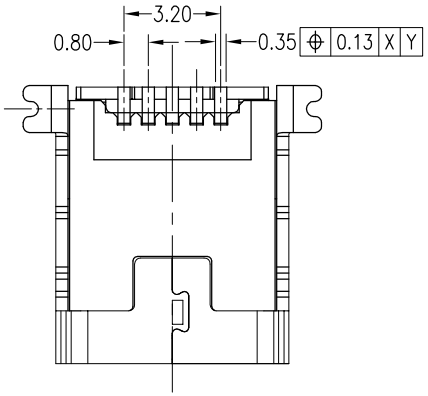
REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE

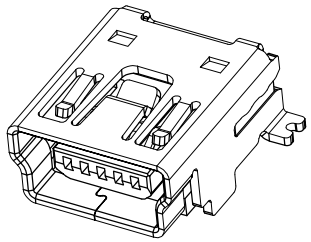


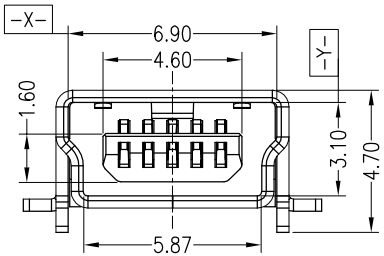


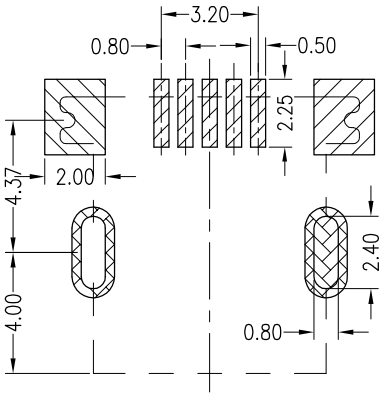












RECOMMANDED PCB LAYOUT

Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v-0

1.2 Contact: copper alloy,t=0.25mm

1.3 Shell: copper alloy,t=0.40mm

2.Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 0.71 Kgf Min.

2.7 Temperature range: -25°C~85°C

A 02 S B X X X X X XX-151

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

外壳材质 1:C2680R-H

外壳电镀 1:Ni50u'' 2:雾T50u'' 3:Ni+Au1u''

端子材质 4:C5191R-EH

主体材质 1:LCP

主体颜色 B:黑色

端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u'' 05:Au5u'';10:Au10u'';15:Au15u'';30:Au30u''

PART NO: A02SBXXXXXXX6-151		MATERAL: SEE NOTE	深圳市顺宏康科技有限公司
MODEL NO: XX		FINSH: SEE NOTE	
UNIT: MM	SIZE: A4	COLOR: SEE NOTE	TITLE: Mini usb 5s B Type前插后贴无柱
TOLERANCE UNSPECIFIED		DR: 夏友红	
.x 0.15		CHK:	DWG NO: SHK-20067 / REV: A
.xx 0.10			
.xxx 0.05		APP:	SCALE: 4:1 / DATE: 2012.06.07
Ang. 1°			